Intel® Desktop Board DN2800MT

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Specifications

Essentials

Status	End of Interactive Support
Launch Date	Q1'12
Board Form Factor	Mini-ITX
Socket	BGA
Embedded Options Available	No
DC Input Voltage Supported	12V
Recommended Customer Price	-
Datasheet	Link

Memory Specifications

Max Memory Size (dependent on memory type)	4 GB
Memory Types	SODIMM DDR3 800/1066
Max # of Memory Channels	1
Max # of DIMMs	2
ECC Memory Supported ‡	No

Graphics Specifications

Integrated Graphics ‡	Yes
Graphics Output	LVDS eDP HDMI VGA
# of Displays Supported ‡	2
Discrete Graphics	None

Expansion Options

PCIe x1 Gen 2.x	1
PCIe x4 Gen 2.x	0
PCIe x8 Gen 2.x	0
PCIe x16 Gen 2.x	0
PCIe x1 Gen 1.x	0
PCIe x4 Gen 1.x	0
PCIe x8 Gen 1.x	0
PCIe x16 Gen 1.x	0
PCIe Mini Card Slot (Half Length)	1
PCIe Mini Card Slot (Full Length)	1

I/O Specifications

USB Revision	2.0
# of USB Ports	8
USB 2.0 Configuration (External + Internal)	4,4
USB 3.0 Configuration (External + Internal)	0
Total # of SATA Ports	2
Max # of SATA 6.0 Gb/s Ports	0
# of eSATA Ports	0
RAID Configuration	N/A

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PCN/MDDS Information

918916: PCN
918917: PCN
918918: PCN
926392: PCN
926393: PCN

# of PATA Ports	0
# of Parallel Ports	1
Parallel Port via Internal Header	Yes
# of Serial Ports	2
Serial Port via Internal Header	Yes
Audio (back channel + front channel)	2,2
Integrated LAN	10/100/1000
S/PDIF Out Connector	1
# of PS2 Ports	0

Package Specifications

Low Halogen Options Available	See MDDS

Advanced Technologies

Intel® HD Audio Technology	Yes

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Refer to Datasheet for formal definitions of product properties and features.

“Announced” SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

“Conflict free” and “conflict-free” means “DRC conflict free”, which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

The Recommended Customer -unit purchase quantities, and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. If sold in bulk, price represents individual unit. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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